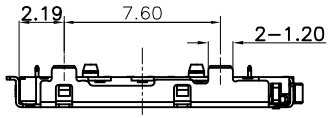
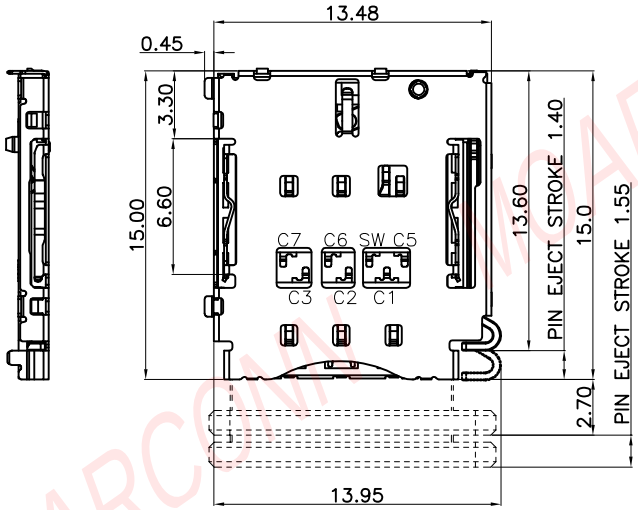
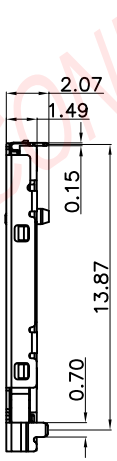
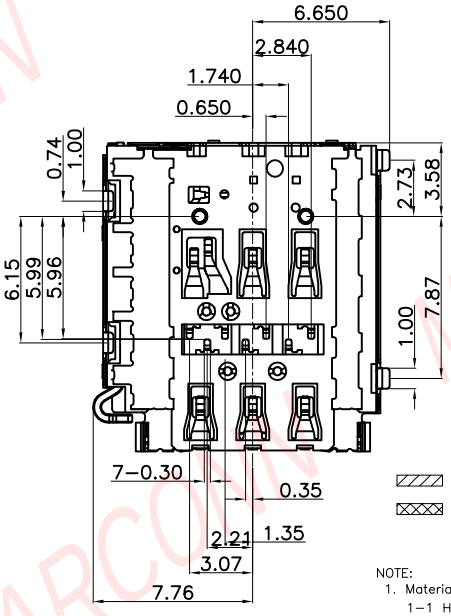
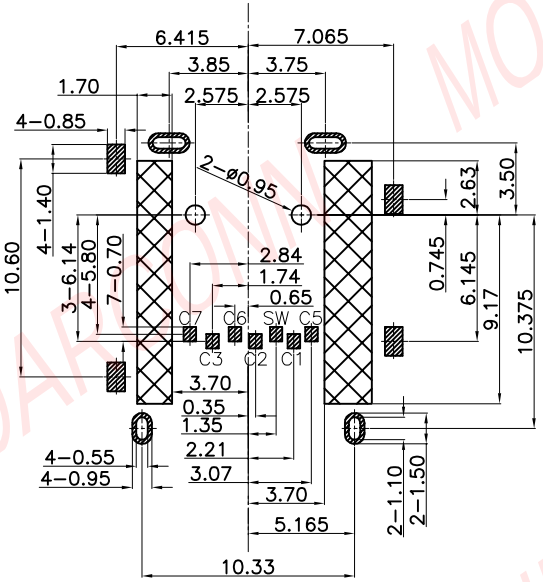
All materials, plating and process meet HF requirements.

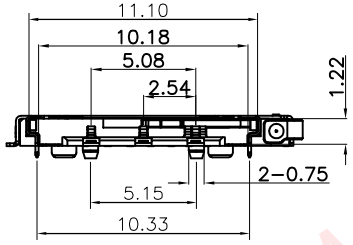


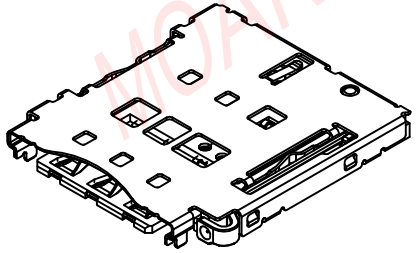












PAD AREA

PATTERN KEEP OUT AREA
via and trace keep out

RECOMMEND P.C.B LAYOUT(TOP VIEW)
(TOlerances Unless Otherwise Spec. ±0.05)

NOTE:
1. Material:
   1-1 Housing:High Temperature Thermoplastic,(LCP S475)Color Black UL 94V-0
   1-2 Contact: Phosphor Bronze(C5210R-SH,T=0.08±0.01mm)
   1-3 Cover: SUS304-H T=0.15±0.03mm
2. Plating:
   2-1 Contact terminal:
   Contact area: Gold 5u" Min. Solder area: Gold 1u" Min .
   Underplating: Ni overall 50U" Min.
   2-2 Cover:
   Underplating: Ni overall 30U" Min. 0.8u"Min.GOLD PLATING ON SOLDET TAIL AREA.
3. Specification:
   3-1.Current Rating :0.5A max.
   3-2.Contact Resistance: 60 mOhms max
   3-3.Insulation Resistance:1000 MOhms min./500VDC
   3-4.Dielectric Withstanding Voltage:500 V AC/1minute
   3-5.Operating Temperature:-25°C to+85°C
   3-6.Tray Insertion force: 40N Max
   3-7.Tray Extraction force: 1~8N
   3-8.Tray Ejector Pin force: 15N Max
4. Product Compliant to HalogenFree+ RoHS2 Directive 2002/95/EC and ELV 2000/53/EC
5. Recommending A Metal More Than 0.15mm Thick.
   Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

COMPOSITION OF DETECTION
CARD DETECT(SW)
C5 ○—○ SW
CARD DETECTION/SWITCH
CARD INSTALLATION:ON NON CARD:OFF

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	-----	NEW RELEASE	Aaron	2023.09.18

MOARCONN®
More Connections Smart Future

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : NANO SIM H1.49 CARD CONN(4DIP带柱)	DRAWING: Aaron	DATE: 2023.12.20	
PRODUCT NO. : NS149-D3131-01	CHECK:	DATE:	
DRAWING NO. : D-NS149-D3131-01	APPROVED:	DATE:	
	SCALE: 1:1	DWG ID: C D	REV.: X0 / PAGE: 1 OF 1

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